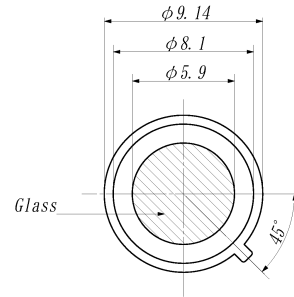


## MTE8087T

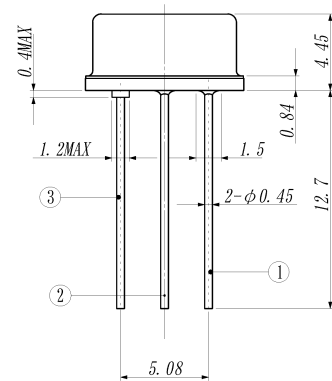
### Features

- Ultra High Power Output
- Chip Size 1.0x1.0mm
- Four Wire Bonds on Die Corners
- Standard 3-lead TO-39 Hermetic Package
- Two Cathode Pins Must Be Externally Connected Together



### Maximum Ratings (Ta=25°C)

Characteristic	Symbol	Max.	Test Condition	Unit
Forward Current	I <sub>F</sub>	500	–	mA
Pulsed Forward Current	I <sub>FP</sub>	10.00	tw=10μ S, T=10mS	A
Reverse Voltage	V <sub>R</sub>	5	–	V
Power Dissipation	P <sub>D</sub>	1000.00	–	mW
Operating Temperature	T <sub>opr</sub>	–50 ~ +100	–	°C
Storage Temperature	T <sub>stg</sub>	–50 ~ +100	–	°C
Junction Temperature	T <sub>j</sub>	100	–	°C
Soldering Temperature	T <sub>sol</sub>	260	for 3 sec. max	°C



- ①Cathode
- ②Cathode
- ③Anode (Case)

TOLERANCE : ±0.15

### Opto-Electrical Characteristics (Ta=25°C)

Characteristic	Symbol	Test Condition	Min	Typ	Max	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =300mA	–	1.50	2.00	V
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =5V	–	–	10	μA
Power Output	PO	I <sub>F</sub> =300mA	–	50.00	–	mW
Half Intensity Beam Angle	θ	–	–	± 45°	–	deg.
Peak Wavelength	λ <sub>p</sub>	I <sub>F</sub> =300mA	–	870	–	nm
Spectral Line Half Width	Δλ	I <sub>F</sub> =300mA	–	45	–	nm

## MTE8087T Graphs

